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## Mask Set Errata for Mask 1L50P

### Introduction

This report applies to mask 1L50P for these products:

- MC68HC908GZ60
- MC68HC908GZ48
- MC68HC908GZ32

The mask set is identified by a 5-character code consisting of a version number, a letter, two numerical digits, and a letter, for example 0J27F. All standard devices are marked with a mask set number and a date code.

Device markings indicate the week of manufacture and the mask set used. The date is coded as four numerical digits where the first two digits indicate the year and the last two digits indicate the work week. For instance, the date code "0301" indicates the first week of the year 2003.

Some MCU samples and devices are marked with an SC, PC, or XC prefix. An SC prefix denotes special/custom device. A PC prefix indicates a prototype device which has undergone basic testing only. An XC prefix denotes that the device is tested but is not fully characterized or qualified over the full range of normal manufacturing process variations. After full characterization and qualification, devices will be marked with the MC or SC prefix.

### SE91-LIN\_Break: LIN Break Delimiter Recognition

**Description:** Under specific timing conditions, the ESCI module will fail to properly detect the break delimiter character in a LIN message. When this occurs, the falling edge that marks the beginning of the actual START bit of the synch 0x55 character is not properly seen by the ESCI. Therefore, the next falling edge to appear on the receive pin after that time (beginning of bit 1 of 0x55 character in LIN) is incorrectly interpreted to be the beginning of a START bit of a new byte.

The timing conditions which cause this to occur are when both:

1. The break character is observed at the receive pin to end approximately on a half bit boundary (about 11.5 bits, 12.5 bits, 13.5 bits, etc.) according to the ESCI local receive clock.
2. The break delimiter received appears to be shorter than one bit time, as measured by the ESCI local receive clock.

The length of the break character as observed by the ESCI at the receive pin (See 1. above) is affected by all of the following:

- The length of the actual transmitted character
- The frequency drift in the local slave clock due to temperature and voltage variations
- Ground shift and edge slew effects in the physical layer

These factors can combine to cause a break character that was transmitted by a master to be nominally 13 bits (as measured by the master clock) to be observed by the slave device as ending on a half bit boundary (13.5 bits as measured by the slave clock, for example).

The break delimiter character only needs to be two or more clock cycles shorter than one bit time to cause the break delimiter to not be detected. (See 2. above)

This situation can occur without violating LIN timing specifications or microcontroller oscillator specifications.

#### Workaround:

One way to properly sample the BREAK delimiter is to switch off the receiver after the rising edge of the delimiter is detected by the arbiter, wait a clock cycle and switch back on the receiver. This will reset the internal sampling clock and will insure accurate recognition of the delimiter.

To implement this solution, in the break symbol interrupt (error interrupt when BKF is set):

1. Set up the arbiter to measure falling- to rising-edge pulse
2. Poll AFIN until set to indicate edge of break delimiter
  - To minimize this polling time, ensure that the LINR bit is set to move the break detection interrupt to the 11th-bit of the break character.
3. Clear RE to disable receiver, execute a NOP, then set RE to re-enable receiver
  - The purpose of the NOP instruction is to prevent a C compiler optimization from deleting this step.
4. Clear FE interrupt by reading data register then exit ISR.

This solution uses polling of the AFIN bit to detect the rising edge of the delimiter. As this is a polling method, the user must evaluate impact of this method to system timing performance.

A non-polling solution can also be implemented using an additional input capture or keyboard interrupt input to detect the rising edge at the end of the break symbol.

The input used must be both:

- Physically connected to the ESCI receive pin
- Able to generate an interrupt upon detection of a rising edge on that pin

To implement this solution, in the break symbol interrupt (error interrupt when BKF is set):

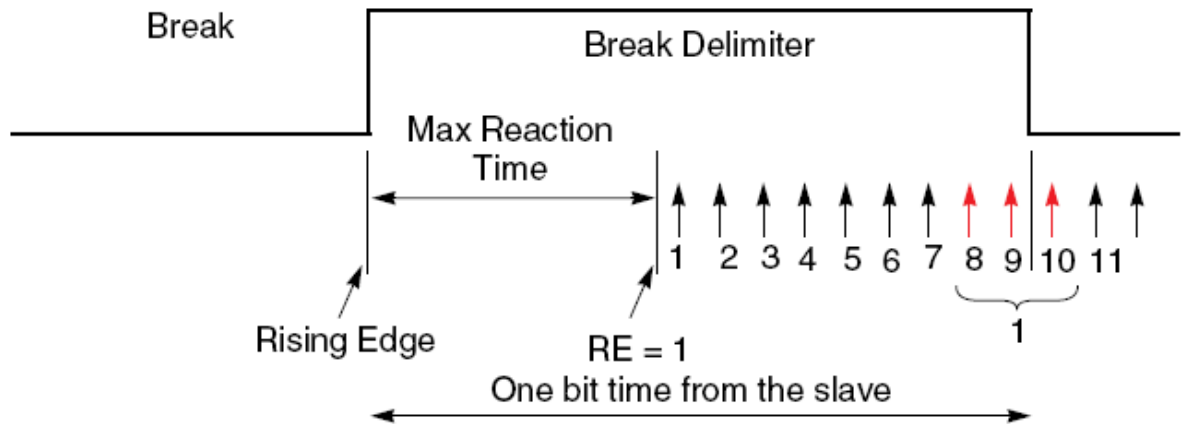
1. Set up the appropriate module to detect rising edge on the receive pin and generate an interrupt
2. Clear the FE and BKF flags by reading the data register, and then exit the ISR

In the rising edge detection interrupt:

1. Clear RE to disable the receiver, execute a NOP, then set RE to re-enable the receiver
  - The purpose of the NOP instruction is to prevent a C compiler optimization from deleting this step.
2. Clear appropriate flags if needed and exit the ISR.

A combination of both previous methods could also be implemented to reduce CPU polling impact. For instance, a periodic interrupt could execute some code during the polling and then return to polling, or the user could put some application code in the polling loop.

The time between when the rising edge actually appears on the receive pin and when the receiver is switched back on is finite and is governed by the timing of the falling edge of the delimiter. The receiver must be switched back on no later than 9/16th of a bit time before the end of the delimiter. See figure below.



**Figure 1. Maximum Time for Other Execution**

From this figure, we also see that the “Maximum Reaction Time” is 7/16<sup>th</sup> slave bit-time.

Translating that into an example LIN system yields:

One bit time at 19200 bps is 52.1 μs.

The LIN 1.3 specification indicates the slave can run at ±14% and the master at ±0.5% of the nominal baudrate. The smallest bit-time the slave might observe is (accounting for accumulated timing errors of a slow slave and fast master):

$$(100\% - 14.5\%) \times (52.1 \mu\text{s}) = (0.855) \times (52.1 \mu\text{s}) = 44.5 \mu\text{s}$$

The Maximum Reaction Time for this example system is  $7/16 \times (44.5 \mu\text{s}) = 19.47 \mu\text{s}$ .

From the instant the rising edge appears on the receive pin (detected via the arbiter AFIN bit or a timer interrupt), the software has to switch the receiver OFF and back ON within 19.47 μs.

Because ground shift in the physical layer might also affect the timing of the falling edge of the START bit of the 0x55 synch byte (i.e., the end of the delimiter), best design practices suggest that the switching of the receiver should be done as quickly as possible after the rising edge is detected. The maximum reaction time calculated above should be treated as a guideline only.

Another workaround which may be used is to temporarily increase the baud rate of the slave device during the reception of the break delimiter. This helps to ensure that the break delimiter appears to the ESCI receiver as greater than one bit time, eliminating timing condition 2 under most operating conditions.

To implement this solution:

1. In the break symbol interrupt (error interrupt when BKF is set), increase the bit rate of the ESCI by a maximum of 9%
2. Remove the 9% speed increase when calculating the baud rate adjustment for that message frame. Only remove the portion of the 9% adjustment that is implemented in the enhanced prescaler (PD+PDFA), as this is the prescaler stage that affects the arbiter measurement of bit time.

The value of 9% allows for differences in clock speeds between master and slave (< 5.5%) and partially compensates for possible effects of a positive ground shift and slew rate effects in the physical layer. These physical layer effects can shorten the length of a recessive pulse (e.g., the break delimiter) by as much as 20.8% (–10.4  $\mu$ s at 20 kbps) of its nominal value and remain within the LIN specification. (Refer to the LIN Physical Layer Specification for more information).

This method is not 100% effective in removing timing condition 2, as the LIN specification does allow enough ground or battery shift to reduce the break delimiter by as much as 20.8%. This means that under absolute worst case conditions in a LIN system, this workaround will not guarantee that a delimiter can be seen.

Ground shift effects cannot be fully compensated for as you would need to increase baud rate by as much as 27%. However, 9% is the maximum safe value to increase baud rate, as it fully compensates for the 5.5% maximum clock difference between master and slave and partially compensates for smaller ground shift effects. If these factors combine, an effective difference of 14.5% in baud rate may be seen with this workaround.

In a LIN system, since the 0x55 character is known to be the next character to be received, the typical guideline of 4.5% difference between two UART devices can be stretched to a little more than 15%. This is because the greatest distance between two falling edges in a 0x55 character is only two bit-times and the UART will resynch on those edges and guarantee reception of the character if both devices are within around 15% of each other's speeds.

### SE76-STOP\_IDD: Excessive Stop I

**Description:** When using port A[7:0] as analog-to-digital converter (ADC) inputs, excessive stop  $I_{DD}$  may result if the input voltage is above  $V_{IL}$  or below  $V_{IH}$ .

**Workaround:** In current sensitive applications, use the other ADC input port inputs on port B and port G.

### SE75-MCLK: MCLK Output Control

**Description:** The MCLK feature on this mask set is selected by write-once CONFIG bits. After it is enabled, the MCLK output cannot be disabled without an MCU reset. Port D, DDR0, does not control the MCLK output function. Therefore, this mask set does not require the port D, DDR0, bit to be selected as an output for the MCLK function to work.

**Workaround:** None

## SE51-OPCODE: Illegal opcode reset

**Description:** If the stop enable bit, STOP, in the CONFIG1 register is 0, the MCU treats the STOP instruction as an illegal opcode. A race condition with 2 signals between the CPU and SIM causes this illegal opcode to recover improperly. The CPU will execute code as if in a runaway condition (Program Counter disrupted). In most cases this improper code execution will generate an additional reset due to a COP timeout, another illegal opcode, or an illegal address fetch. Other behaviors can occur depending on the execution of the code accessed by the CPU.

**Workaround:** Use another illegal opcode, for instance \$32, instead of STOP to force an illegal opcode reset.

## SE17-MSCAN: MSCAN Extended ID Rejected if STUFF Bit Between ID16 and ID15

**Description:** For 32-bit and 16-bit identifier acceptance modes, an extended ID CAN frame with a stuff bit between ID16 and ID15 can be erroneously rejected, depending on IDAR0, IDAR1, and IDMR1.

Extended IDs (ID28-ID0) which generate a stuff bit between ID16 and ID15:

where x = 0 or 1 (don't care) and \* = pattern for ID28 to ID18 (see following).

IDAR0	IDAR1	IDAR2	IDAR3
*****	***1111x	xxxxxxx	xxxxxxx
where x = 0 or 1 (don't care) and * = pattern for ID28 to ID18 (see following).			

Affected extended IDs (ID28 - ID18) patterns:

- a) xxxxxxxxxx01 exceptions: 00000000001  
01111100001  
xxxx1000001 except 11111000001
- b) xxxxx100000 exception: 01111100000
- c) xxxx01111111 exception: 00000111111
- d) x01111110000
- e) 10000000000
- f) 11111111111
- g) 10000011111

When an affected ID is received, an incorrect value is compared to the 2nd byte of the filter (IDAR1 and IDAR5, plus IDAR3 and IDAR7 in 16-bit mode). This incorrect value is the shift register contents before ID15 is shifted in (i.e. right shifted by 1).

**Workaround:** If the problematic IDs cannot be avoided, the workaround is to mask certain bits with IDMR1 (and IDMR5, plus IDMR3 and IDMR7 in 16-bit mode).

Example 1: to receive the message IDs

xxxx xxxx x011 111x xxxx xxxx xxxx xxxx  
IDMR1 etc. must be 111x xxx1, i.e. ID20,19,18,15 must be masked.

Example 2: to receive the message IDs

xxxx 0111 1111 111x xxxx xxxx xxxx xxxx  
IDMR1 etc. must be 1xxx xxx1, i.e. ID20 and ID15 must be masked.

In general, using IDMR1 etc. 1111 xxx1, i.e. masking ID20,19,18,SRR,15, hides the problem.

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 Tokyo 153-0064  
 Japan  
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Freescale Semiconductor China Ltd.  
 Exchange Building 23F  
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